## Triple Non-Inverting Schmitt-Trigger Buffer

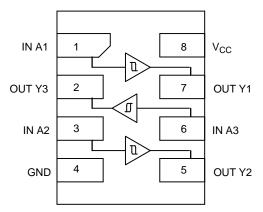
The NLU3G17 MiniGate<sup>™</sup> is an advanced high–speed CMOS triple non–inverting Schmitt–trigger buffer in ultra–small footprint.

The NLU3G17 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

The NLU3G17 can be used to enhance noise immunity or to square up slowly changing waveforms.

#### Features

- High Speed:  $t_{PD} = 4.0 \text{ ns} (Typ) @ V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 1 \ \mu A$  (Max) at  $T_A = 25^{\circ}C$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb–Free Devices





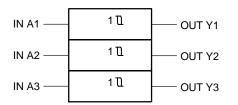


Figure 2. Logic Symbol

FUNCTION TABLE				
Α	Y			
L	L			
Н	Н			

#### **PIN ASSIGNMENT**

IN A1
OUT Y3
IN A2
GND
OUT Y2
IN A3
OUT Y1
V <sub>CC</sub>



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### MARKING DIAGRAMS UDFN8 UZM CASE 517AJ UDFN8 1.45 x 1.0 ΧМ CASE 517BZ o UDFN8 1.6 x 1.0 ΧМ CASE 517BY UDFN8 1.95 x 1.0 ХМ CASE 517CA UZ, D or LX = Specific Device Code

UZ, D or LX = Specific Device Code M = Date Code

= Pb–Free Package

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage	-0.5 to +7.0	V
V <sub>OUT</sub>	DC Output Voltage	-0.5 to +7.0	V
I <sub>IK</sub>	DC Input Diode Current V <sub>IN</sub> < GND	-20	mA
I <sub>OK</sub>	DC Output Diode Current V <sub>OUT</sub> < GND	±20	mA
Ι <sub>Ο</sub>	DC Output Source/Sink Current	±12.5	mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin	±25	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	±25	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias	150	°C
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
ILATCHUP	Latchup Performance Above V <sub>CC</sub> and Below GND at 125°C (Note 2)	±500	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
Tested to EIA / JESD78.

## **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage	1.65	5.5	V
V <sub>IN</sub>	Digital Input Voltage	0	5.5	V
V <sub>OUT</sub>	Output Voltage	0	5.5	V
T <sub>A</sub>	Operating Free–Air Temperature	-55	+125	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate $V_{CC}$ = 3.3 V ± 0.3 V $V_{CC}$ = 5.0 V ± 0.5 V	0 0	No Limit No Limit	ns/V

## DC ELECTRICAL CHARACTERISTICS

			V <sub>CC</sub>		T <sub>A</sub> = 25 °C	;	<b>T</b> <sub>A</sub> = -	⊦85°C		55°C to 5°C	
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V <sub>T+</sub>	Positive Threshold Voltage		3.0 4.5 5.5	1.85 2.86 3.50	2.0 3.0 3.6	2.2 3.15 3.85		2.2 3.15 3.85		2.2 3.15 3.85	V
V <sub>T-</sub>	Negative Threshold Voltage		3.0 4.5 5.5	0.9 1.35 1.65	1.5 2.3 2.9	1.65 2.46 3.05	0.9 1.35 1.65		0.9 1.35 1.65		V
V <sub>H</sub>	Hysteresis Voltage		3.0 4.5 5.5	0.30 0.40 0.50	0.57 0.67 0.74	1.20 1.40 1.60	0.30 0.40 0.50	1.20 1.40 1.60	0.30 0.40 0.50	1.20 1.40 1.60	V
V <sub>OH</sub>	Minimum High–Level Output	$V_{IN} \ge V_{T+MAX}$ $I_{OH} = -50 \ \mu A$	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
	Voltage	$\begin{array}{l} V_{IN} \geq V_{T+MAX} \\ I_{OH} = -4 \text{ mA} \\ I_{OH} = -8 \text{ mA} \end{array}$	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		
V <sub>OL</sub>	Maximum Low–Level Output	$V_{IN} \le V_{T-MIN}$ $I_{OL} = 50 \ \mu A$	2.0 3.0 4.5		0 0 0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
	Voltage	$\begin{array}{l} V_{IN} \leq V_{T-MIN} \\ I_{OL} = 4 \text{ mA} \\ I_{OL} = 8 \text{ mA} \end{array}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I <sub>IN</sub>	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I <sub>CC</sub>	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5.5			1.0		10		40	μΑ

#### AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$ )

		V <sub>CC</sub>	Test		T <sub>A</sub> = 25 °	с	T <sub>A</sub> =	+85°C	T <sub>A</sub> = -5 +12	55°C to 5°C	
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub> ,	Propagation Delay,	3.0 to	C <sub>L</sub> = 15 pF		7.0	12.8	1.0	15	1.0	17	ns
t <sub>PHL</sub>	Input Ă to Output Ÿ	3.6	C <sub>L</sub> = 50 pF		8.5	16.3	1.0	18.5	1.0	20.5	
		4.5 to	C <sub>L</sub> = 15 pF		4.0	8.6	1.0	10	1.0	11.5	
		5.5	C <sub>L</sub> = 50 pF		5.5	10.6	1.0	12	1.0	13.5	
C <sub>IN</sub>	Input Capacitance				5.0	10		10		10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 3)	5.0			7.0						pF

3.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$ .  $C_{PD}$  is used to determine the no-load dynamic power consumption:  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$ .

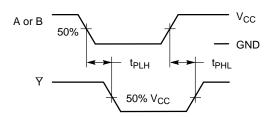
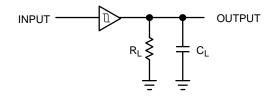


Figure 3. Switching Waveforms



A 1-MHz square input wave is recommended for propagation delay tests.

#### Figure 4. Test Circuit

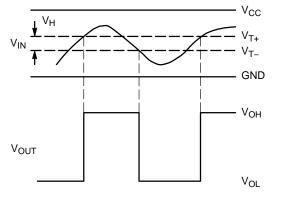
V<sub>CC</sub>

 $V_{T+}$ 

V<sub>T-</sub> GND

VOH

VOL



(a) A Schmitt-Trigger Squares Up Inputs With Slow Rise and Fall Times

(b) A Schmitt-Trigger Offers Maximum Noise Immunity

#### Figure 5. Typical Schmitt-Trigger Applications

Vout

Vн

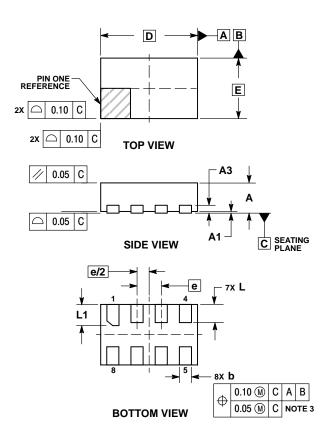
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NLU3G17MUTAG	UDFN8 (Pb-Free)	3000 / Tape & Reel
NLU3G17DMUTCG	UDFN8, 1.95 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLU3G17EMUTCG	UDFN8, 1.6 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLU3G17FMUTCG	UDFN8, 1.45 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

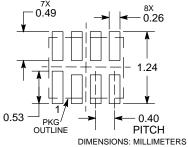
UDFN8 1.6x1.0, 0.4P CASE 517BY ISSUE O



- NOTES:
   DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
   CONTROLLING DIMENSION: MILLIMETERS.
   DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
   PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

BURRS AND MOLD FL/						
	MILLIN	MILLIMETERS				
DIM	MIN	MIN MAX				
Α	0.45	0.55				
A1	0.00	0.05				
A3	0.13	0.13 REF				
b	0.15	0.25				
D	1.60	BSC				
E	1.00	BSC				
е	0.40 BSC					
L	0.25	0.35				
L1	0.30	0.40				

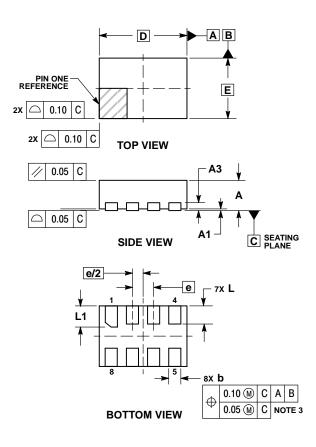
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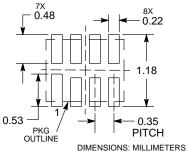
UDFN8 1.45x1.0, 0.35P CASE 517BZ ISSUE O



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BURRS AND MOLD FL						
	MILLIN	MILLIMETERS				
DIM	MIN	MIN MAX				
Α	0.45	0.55				
A1	0.00	0.05				
A3	0.13 REF					
b	0.15	0.25				
D	1.45	BSC				
Е	1.00	1.00 BSC				
е	0.35 BSC					
L	0.25 0.35					
L1	0.30	0.40				

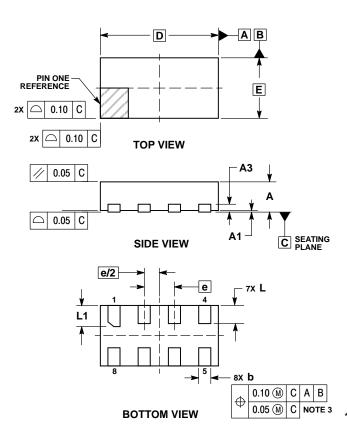
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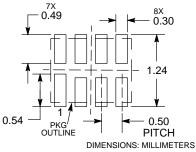
UDFN8 1.95x1.0, 0.5P CASE 517CA ISSUE O



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   PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

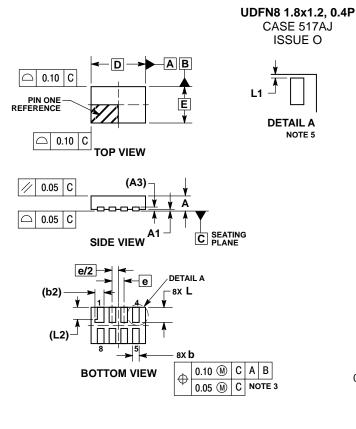
BURRS AND MOLD FL						
	MILLIN	MILLIMETERS				
DIM	MIN	MAX				
Α	0.45	0.55				
A1	0.00	0.05				
A3	0.13 REF					
b	0.15	0.25				
D	1.95	BSC				
E	1.00	BSC				
е	0.50 BSC					
L	0.25 0.35					
L1	0.30	0.40				

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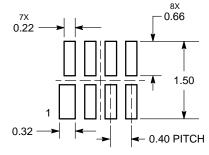


NOTES

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- 3.
- ASIME 114-3M, 1994. CONTROLLING DIMENSION: MILLIMETERS. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP. MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE. FLASH MAY NOT EXCEED 0.03 ONTO POTTOM NOT EXCEED 0.03 ONTO BOTTOM
- SURFACE OF TERMINALS DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS. 5.

	MILLIMETERS				
DIM	MIN	MAX			
Α	0.45	0.55			
A1	0.00	0.05			
A3	0.127	0.127 REF			
b	0.15	0.25			
b2	0.30	REF			
D	1.80	BSC			
Е	1.20	BSC			
е	0.40	BSC			
L	0.45	0.55			
L1	0.00	0.03			
L2	0.40	REF			

#### MOUNTING FOOTPRINT SOLDERMASK DEFINED



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